AM

- 1/1 JAPIO (C) JPO- image
- PN JP 09162090 A 19970620 [JP09162090]
- TI SEMICONDUCTOR BASIC MATERIAL AND PRODUCTION THEREOF
- IN SATO NOBUHIKO: SAKAGUCHI KIYOBUMI; YONEHARA TAKAO
- PA CANON INC
- AP JP26438696 19961004 [1996JP-0264386]
- PR JP07260100 19951006 [1995JP-0260100]
- IC1 H01L-021/02
- IC2 H01L-021/20 H01L-021/265 H01L-027/12
- AB PROBLEM TO BE SOLVED: To provide a method for producing a flat SOT basic material having sufficient quality with high reproducibility while saving the resource and realizing cost reduction by reusing the material.
  - SOLUTION: The method for producing a semiconductor basic material comprises a step for making porous an Si basic material and to form a porous Si layer 42 at least on the surface thereof, and a step for forming a porous Si layer 44 having high porosity in the porous Si layer 42. The step for forming a high porosity layer can be carried out by injecting ions into a porous Si layer at a specified projection range, or varying the current density at the time of anodic formation during the step for forming a high porosity layer. In this regard, a nonporous single crystal Si layer 43 is grown epitaxially on the porous Si layer 42. Subsequently, the surface of porous Si layer 42 is pasted to a supporting basic body 45 and separated through a porous Si layer 44 having high porosity. Finally, the porous Si layer 42 is removed by selective etching.
  - COPYRIGHT: (C) 1997, JPO